



PK1042 (v1.0) February 7, 2020

100% Material Declaration Data Sheet for Spartan-II FPGA Family PQ208 Package

Average Weight : 5.5430 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silver Epoxy	Silver	7440-22-4	85.3		0.009566	0.17258%
	Epoxy resin	Trade Secret	5.4		0.008160	
	Organic anhydride	Trade Secret	3.1		0.000517	
	A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl) phenol; 4-allyl-6-[3-[6-[3-[6-[3-(4-allyl-2, 6-bis (2,3-epoxypropyl) phenoxy)-2-hydroxypropyl	-	3.1		0.000297	
	Anhydride	Trade Secret	3.1		0.000297	
Die	Silicon	7440-21-3	100.00		0.064259	1.15928%
Gold Wire	Gold	7440-57-5	99.0475		0.005000	0.09020%
	Palladium	7440-05-3	0.95		0.004952	
	Calcium	7440-70-2	0.002		0.000048	
	Beryllium	7440-41-7	0.0005		0.000000	
					0.000000	
Mold Compound	Epoxy Resin	Trade Secret	10		4.708150	84.93866%
	Phenol Resin	Trade Secret	5		0.470815	
	Silica (Amorphous) A	60676-86-0	74		0.235408	
	Silica (Amorphous) B	7631-86-9	10		3.484031	
	Carbon Black	1333-86-4	1		0.470815	
Heat Spreader	Aluminum	7429-90-5	99.545		0.399000	7.19827%
	Iron	7439-89-6	0.2		0.397185	
	Silicon	7440-21-3	0.125		0.000798	
	Zinc	7440-66-6	0.025		0.000499	
	Copper	7440-50-8	0.025		0.000100	
	Manganese	7439-96-5	0.025		0.000100	
	Magnesium	7439-95-4	0.025		0.000100	
	Titanium	7440-32-6	0.015		0.000060	
	Additives	-	0.015		0.000060	
					0.000060	
Leadframe Tape	NBR	9003-18-3	14		0.006000	0.10824%
	Phenol Resin	28453-20-5	14		0.000840	
	Bismaleimide	79922-55-7	14		0.000840	
	Polyimide Film	Trade Secret	58		0.003480	
Leadframe	Nickel Plating	7440-02-0	0.325		0.351025	6.33276%
	Palladium Plating	7440-05-3	0.0175		0.001141	
	Gold Plating	7440-57-5	0.004		0.000061	
	Copper	7440-50-8	95.5535		0.000014	
	Magnesium	7439-95-4	0.175		0.335417	
	Silicon	7440-21-3	0.725		0.000614	
	Nickel	7440-02-0	3.2		0.002545	
				0.011233		

Revision History

Date	Version	Description of Revisions
2/7/2020	1.0	Initial Xilinx release (XCN18024).

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